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SHARP

MOBILE LIQUID CRYSTAL DISPLAY GROUP

SHARP CORPORATION

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MOBILE LIQUID CRYSTAL DISPLAY **GROUP**

SPECIFICATION

DEVICE SPECIFICATION FOR

TFT-LCD module

MODEL No. LQ043Y1DX07

☐ CUSTOMER'S	APPROVAL
DATA	
ВҮ	

PRESENTED

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RECORDS OF REVISION

MODEL No: LQ043Y1DX07 SPEC No: LCP-2210046A

DATE	REVISED	PAGE	SUMMARY	NOTE
	LCP-2210046		-	1st Issue
Nov.08.2010	LCP-2210046A	18	Correct Table 14. NTSC ratio 70%typ → 90%typ	2nd Issue
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ODo not use the device for equipment that requires an extreme level of reliability, such as aerospace applications, telecommunication equipment (trunk lines), nuclear power control equipment and medical or other equipment for life support.

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instructions and the precautions specified in these specification sheets.

OContact and consult with a SHARP sales representative for any questions about this device.

[For handling and system design]

- (1) Do not scratch the surface of the polarizer film as it is easily damaged.
- (2) If the cleaning of the surface of the LCD panel is necessary, wipe it swiftly with cotton or other soft cloth. Do not use organic solvent as it damages polarizer.
- (3) Water droplets on polarizer must be wiped off immediately as they may cause color changes, or other defects if remained for a long time.
- (4) Since this LCD panel is made of glass, dropping the module or banging it against hard objects may cause cracks or fragmentation.
- (5) Epoxy resin (amine series curing agent), silicone adhesive material (dealcoholization series and oxime series), tray forming agent (azo compound) etc, in the cabinet or the packing materials may induce abnormal display with polarizer film deterioration regardless of contact or noncontact to polarizer film.

Check carefully that gas from materials used in system housing or packaging do not hart polarizer. Be sure to confirm the component of them.

(6) Liquid crystal material will freeze below specified storage temperature range and it will not get back to normal quality even after temperature comes back within specified temperature range. Liquid crystal material will become isotropic above specified temperature range and may not get back to normal quality. Keep the LCD module always within specified temperature range.

- (7) Do not expose LCD module to the direct sunlight or to strong ultraviolet light for long time.
- (8) If the LCD driver IC (COG) is exposed to light, normal operation may be impeded. It is necessary to design so that the light is shut off when the LCD module is mounted.
- (9) Do not disassemble the LCD module as it may cause permanent damage.
- (10) As this LCD module contains components sensitive to electrostatic discharge, be sure to follow the instructions in below.
 - ① Operators

Operators must wear anti-static wears to prevent electrostatic charge up to and discharge from human body.

② Equipment and containers

Process equipment such as conveyer, soldering iron, working bench and containers may possibly generate electrostatic charge up and discharge. Equipment must be grounded through 100Mohms resistance. Use ion blower.

③ Floor

Floor is an important part to leak static electricity which is generated from human body or equipment.

There is a possibility that the static electricity is charged to them without leakage in case of insulating floor, so the

countermeasure(electrostatic earth: $1 \times 10^8 \Omega$) should be made.

4 Humidity

Proper humidity of working room may reduce the risk of electrostatic charge up and discharge. Humidity should be kept over 50% all the time.

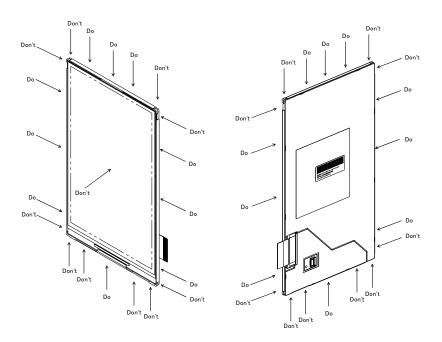
⑤Transportation/storage

Storage materials must be anti-static to prevent causing electrostatic discharge.

6Others

Protective film is attached on the surface of LCD panel to prevent scratches or other damages. When removing this protective film, remove it slowly under proper anti-ESD control such as ion blower.

- (11) Hold LCD very carefully when placing LCD module into the system housing. Do not apply excessive stress or pressure to LCD module. Do not to use chloroprene rubber as it may affect on the reliability of the electrical interconnection.
- (12) Do not hold or touch LCD panel to flex interconnection area as it may be damaged.
- (13) As the binding material between LCD panel and flex connector mentioned in 12) contains an organic material, any type of organic solvents are not allowed to be used. Direct contact by fingers is also prohibited.
- (14) When carrying the LCD module, place it on the tray to protect from mechanical damage. It is recommended to use the conductive trays to protect the CMOS components from electrostatic discharge. When holding the module, hold the Plastic Frame of LCD module so that the panel, COG and other electric parts are not damaged.



- (15) Do not touch the COG's patterning area. Otherwise the circuit may be damaged.
- (16) Do not touch LSI chips as it may cause a trouble in the inner lead connection.
- (17) Place a protective cover on the LCD module to protect the glass panel from mechanical damages.
- (18) LCD panel is susceptible to mechanical stress and even the slightest stress will cause a color change in background and pooling. So make sure the LCD panel is placed on flat plane without any continuous twisting, bending or pushing stress.
- (19) Protective film is placed onto the surface of LCD panel when it is shipped from factory. Make sure to peel it off before assembling the LCD module into the system. Be very careful not to damage LCD module by electrostatic discharge when peeling off this protective film. Ion blower and ground strap are recommended.
- (20) Make sure the mechanical design of the system in which the LCD module will be assembled matches specified viewing angle of this LCD module.
- (21) This LCD module does not contain nor use any ODS (1,1,1-Trichloroethane, CCL4), CFCS, Carbon tetrachloride, Halon in all materials used, in all production processes.

[For operating LCD module]

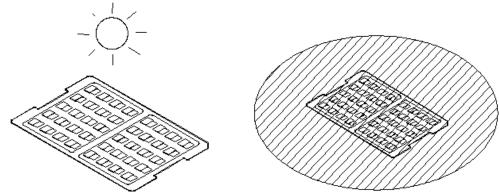
- (1) Do not operate or store the LCD module under outside of specified environmental conditions.
- (2) At the shipment, adjust the contrast of each LCD module with electric volume. LCD contrast may vary from panel to panel depending on variation of LCD power voltage from system.
- (3) As opt-electrical characteristics of LCD will be changed, dependent on the temperature, the confirmation of display quality and characteristics has to be done after temperature is set at 25 °C and it becomes stable.

[Precautions for Storage]

- (1) Do not expose the LCD module to direct sunlight or strong ultraviolet light for long periods. Store in a dark place.
- (2) The liquid crystal material will solidify if stored below the rated storage temperature and will become an isotropic liquid if stored above the rated storage temperature, and may not retain its original properties. Only store the module at normal temperature and humidity (25±5°C,60±10%RH) in order to avoid exposing the front polarizer to chronic humidity.

- (3) Keeping Method
 - a. Don't keeping under the direct sunlight.
- b. Keeping in the tray under the dark place.





- (1) Do not operate or store the LCD module under outside of specified environmental conditions.
- (2) Be sure to prevent light striking the chip surface.

[Other Notice]

- (1) Do not operate or store the LCD module under outside of specified environmental conditions.
- (2) As electrical impedance of power supply lines (VCI/VDDIO-GND) are low when LCD module is working, place the de-coupling capacitor near by LCD module as close as possible.
- (3) Reset signal must be sent after power on to initialize LSI. LSI does not function properly until initialize it by reset signal.
- (4) Generally, at power on, in order not to apply DC charge directly to LCD panel, supply logic voltage first and initialize LSI logic function including polarity alternation. Then supply voltage for LCD bias. At power off, in order not to apply DC charge directly to LCD panel, execute Power OFF sequence and Discharge command.
- (5) Don't touch to FPC surface, exposed IC chip, electric parts and other parts, to any electric, metallic materials.
- (6) No bromide specific fire-retardant material is used in this module.
- (7) Do not display still picture on the display over 2 hours as this will damage the liquid crystal.
- (8)This product doesn't support active backlight function. Use active back light function with this product at your discretion and responsibility.

[Precautions for Discarding Liquid Crystal Modules]

COG: After removing the LSI from the liquid crystal panel, dispose of it in a similar way to circuit boards from electronic devices.

LCD panel: Dispose of as glass waste. This LCD module contains no harmful substances. The liquid crystal panel contains no dangerous or harmful substances. The liquid crystal panel only contains an extremely small amount of liquid crystal (approx.100mg) and therefore it will not leak even if the panel should break.

-Its median lethal dose (LD50) is greater than 2,000 mg/kg and a mutagenetic (Aims test: negative) material is employed.

FPC: Dispose of as similar way to circuit board from electric device.

1. Application

This data sheet is to introduce the specification of LQ043Y1DX07 active matrix 16.7Mcolors LCD module. LCD module is controlled by Driver IC (HX8363A/RAMless).

If any problem occurs concerning the items not stated in this specification, it must be solved sincerely by both parties after deliberation.

As to basic specification of driver IC refer to the IC specification and handbook.

2. Construction and Outline

This module is a color transmissive, high contrast, wide viewing angle and active matrix LCD module incorporating amorphous silicon TFT (Thin Film Transistor), named ASV LCD (Advanced Super View LCD).

Construction: LCD panel, Driver (COG), FPC with electric components, 8 white LEDs prism sheet, diffuser, light guide and reflector, plastic frame and metal frame to fix them mechanically.

Outline: See page ** (Fig.1 Outline Dimensions)

Connection: Connector (Panasonic AXE660124)

There shall be no scratches, stains, chips, distortions and other external drawbacks that may affect the display function.

Rejection criteria shall be noted in Inspection Standard.

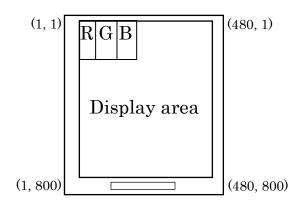
3. Mechanical (Physical) Specifications

Table1

Item	Specifications	Unit	Remarks
Screen size	10.9 (4.30" type) Diagonal	cm	
Active area	56.16(H)×93.60(V)	mm	
Pixel format	480(H)×800(V)	pixel	
Fixerionnat	1 Pixel =R+G+B dots	-	
Pixel pitch	0.117(H)×0.117(V)	mm	
Pixel configuration	R,G,B vertical stripes	-	
Display mode	Normally black	-	
Unit outline dimensions	62.46(W)×105.9(H)×2.1(D)	mm	[Note3-1]
Mass	30	g	
Surface hardness	3H(Initial)	-	Pencil hardness

[Note3-1] The above-mentioned table indicates module sizes without some projections and FPC. For detailed measurements and tolerances, please refer to Fig.1 Outline Dimensions.

4. Pixel Configuration



5. Input Terminal Names and Functions

Table2

1 GND - Ground 2 GND - Ground 3 NC - No Connection 4 SDO O SPI I/F data out from LCM 5 SDI I SPI I/F data out from LCM 6 GND - Ground 7 SCL I SPI I/F chip select 8 CSX I Device reset signal 10 GND - Ground 11 DR7 I Red data signal (MSB) 12 DR6 I Red data signal 13 DR5 I Red data signal 14 DR4 I Red data signal 15 GND - Ground 16 DR3 I Red data signal 17 DR2 I Red data signal 18 DR1 I Red data signal 19 DR0 I/O Red data signal 10 GND - Ground 11 Ground 11 GR7 Ground 11 GR7 Ground 12 DR6 I Red data signal 13 DR5 I Red data signal 14 DR4 I Red data signal 15 GND - Ground 16 DR3 I Red data signal 17 DR2 I Red data signal 18 DR1 I Red data signal 19 DR0 I/O Red data signal 19 DR0 I/O Red data signal 20 GND - Ground 21 DG7 I Green data signal (MSB) 22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal 29 DG0 I Green data signal 31 DB7 I Green data signal 32 DB6 I Green data signal 33 DB5 I Green data signal 34 DB4 - Blue data signal (MSB) 35 DB6 I Green data signal	Pin No.	Symbol	I/O	Description	Remarks
2 GND - Ground 3 NC - No Connection 4 SDO O SPI I/F data out from LCM 5 SDI I SPI I/F data out from LCM 6 GND - Ground 7 SCL I SPI I/F chip select 8 CSX I SPI I/F chip select 9 RESX I Device reset signal 10 GND - Ground 11 DR7 I Red data signal (MSB) 12 DR6 I Red data signal 13 DR5 I Red data signal 14 DR4 I Red data signal 15 GND - Ground 16 DR3 I Red data signal 17 DR2 I Red data signal 18 DR1 I Red data signal 19 DR0 I/O Ground 10 GND - Ground 11 Ground 11 Ground 12 Ground 13 DR5 I Red data signal 14 DR4 I Red data signal 15 GND - Ground 16 DR3 I Red data signal 17 DR2 I Red data signal 18 DR1 I Green data signal 19 DR0 I/O Ground 20 GND - Ground 21 DG7 I Green data signal (LSB) 22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 II Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal 31 DB7 I Blue data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal	1			<u> </u>	
3					
SPI I SPI I/F data In to LCM		NC	-	No Connection	
Ground Ground Floor Ground Floor Floor	4	SDO	0	SPI I/F data out from LCM	
7 SCL	5	SDI	I	SPI I/F data In to LCM	
SPI I/F chip select	6	GND	-	Ground	
9 RESX I Device reset signal 10 GND - Ground 11 DR7 I Red data signal (MSB) 12 DR6 I Red data signal 13 DR5 I Red data signal 14 DR4 I Red data signal 15 GND - Ground 16 DR3 I Red data signal 17 DR2 I Red data signal 18 DR1 I Red data signal 19 DR0 I/O Red data signal (LSB) (10kΩ±5% Pull-Down GND) Red data signal 20 GND - Ground 21 DG7 I Green data signal (MSB) 22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3	7	SCL	I	SPI I/F clock	
10	8	CSX	I	SPI I/F chip select	
11	9	RESX	I	Device reset signal	
12	10	GND	-	Ground	
13	11	DR7	ı	Red data signal (MSB)	
14 DR4 I Red data signal 15 GND - Ground 16 DR3 I Red data signal 17 DR2 I Red data signal 18 DR1 I Red data signal (LSB) 19 DR0 I/O Red data signal (LSB) (10kΩ±5% Pull-Down GND) Ground 20 GND - Ground 21 DG7 I Green data signal (MSB) 22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal 32 DB6	12	DR6	ı	Red data signal	
15	13	DR5	ı	Red data signal	
16	14	DR4	ı	Red data signal	
17	15	GND	-	Ground	
18	16	DR3	ı	Red data signal	
19	17	DR2	I	Red data signal	
O O O O O O O O O O	18	DR1	I	Red data signal	
21 DG7 I Green data signal (MSB) 22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	19	DR0	I/O	Red data signal (LSB) (10kΩ±5% Pull-Down GND)	
22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	20	GND	-		
22 DG6 I Green data signal 23 DG5 I Green data signal 24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	21	DG7	ı	Green data signal (MSB)	
24 DG4 I Green data signal 25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	22	DG6	I	Green data signal	
25 GND - Ground 26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	23	DG5	I	Green data signal	
26 DG3 I Green data signal 27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	24	DG4	I	Green data signal	
27 DG2 I Green data signal 28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	25	GND	-	Ground	
28 DG1 I Green data signal 29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	26	DG3	I	Green data signal	
29 DG0 I Green data signal (LSB) 30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	27	DG2	ı	Green data signal	
30 GND - Ground 31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	28	DG1	ı	Green data signal	
31 DB7 I Blue data signal (MSB) 32 DB6 I Blue data signal 33 DB5 I Blue data signal	29	DG0	I	Green data signal (LSB)	
32 DB6 I Blue data signal 33 DB5 I Blue data signal	30	GND		Ground	
33 DB5 I Blue data signal	31	DB7		Blue data signal (MSB)	
	32	DB6		Blue data signal	
34 DB4 - Blue data signal	33	DB5		Blue data signal	
	34	DB4	-	Blue data signal	

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Pin No.	Symbol	I/O	Description	Remarks
35	GND	-	Ground	
36	DB3	1	Blue data signal	
37	DB2	ı	Blue data signal	
38	DB1	ı	Blue data signal	
39	DB0	I	Blue data signal (LSB)	
40	DE	ı	Data enable	
41	GND	-	Ground	
42	PCLK	I	Pixel clock signal	
43	GND	-	Ground	
44	HS	I	Horizontal synchronous signal	
45	VS	ı	Vertical synchronous signal	
46	VDDIO	-	Power supply for I/O	
47	VCI	-	Power supply for analog	
48	NC	-	No Connection	
49	LEDK	-	Power Supply for LED(Cathode)	Connected to pin-50
50	LEDK	-	Power Supply for LED(Cathode)	Connected to pin-49
51	LEDA	-	Power Supply for LED(Anode)	
52	GND	-	Ground	
53	NC	-	No Connection	
54	GND-TP	-	By pass to TP connector	
55	S1	-	By pass to TP connector	
56	S2	-	By pass to TP connector	
57	S3	-	By pass to TP connector	
58	VDD-TP	-	By pass to TP connector	
59	S4	-	By pass to TP connector	
60	GND-TP	-	By pass to TP connector	

6. Absolute Maximum Ratings

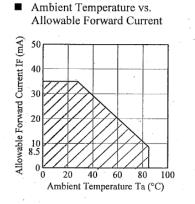
Table 3 GND=0V

Parameter	Symbol	Conditions	Rated value	Unit	Remarks
Driver IC (Analog)	VCI	Ta=+25℃	-0.3 ~ +4.6	V	[NoteC 4]
Power Supply Voltage					【Note6-1】
Driver IC (Digital)	VDDIO	Ta=+25℃	-0.3 ~ +4.6	V	[Note6-1]
Power Supply Voltage					[Noteo-1]
Temperature for storage	Tstg	-	-40 ~ +80	°C	[Note6-2]
Temperature for operation	Topr	-	-20 ~ +60	°C	[Note6-2]
LED Input electric current	ILED	Ta=+25°C	35	mA	[Note6-3]

[Note6-1] Voltage applied to GND pins. GND pin conditions are based on all the same voltage (0V). Always connect all GND externally and use at the same voltage.

[Note6-2] Humidity : 95%RHMax.(at Ta≤40°C). Maximum wet-bulb temperature is less than 39°C(at Ta>40°C). Condensation of dew must be avoided.

[Note6-3] Ambient temperature and the maximum input are fulfilling the following operating conditions. **Please refer to specification of "Himax HX8363A" for detail.



7. Electrical Characteristics

7-1. TFT-LCD Panel Driving Section

Table 4 GND=0V

CITE OF								
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remarks		
Driver IC(Analog) Power Supply Voltage	VCI	2.75	3.0	3.3	V	【Note7-1】		
Driver IC(Digital) Power Supply Voltage	VDDIO	1.65	2.6	3.3	V	【Note7-1】		
Input voltage (Low)	V _{IL}	0	-	0.3VDDIO	V	[Note7-2]		
Input voltage (High)	V _{IH}	0.7VDDIO	-	VDDIO	V	[Note7-2]		
Input current (Low)	I _{IL}	-1	-	-	μA			
Input current (High)	I _{IH}	-	-	1	μA			
Output voltage (Low)	V _{oL}	0	-	0.2VDDIO	V	I _{oL} =+0.1mA		
Output voltage (High)	V _{oH}	0.8VDDIO	-	VDDIO	V	I _{oH} =-0.1mA		
		-	88	140	mW	[Note7-3]		
Power consumption	Pnorm	-	76	-	mW	[Note7-4]		
Power consumption	FIIOIIII		37	-	mW	[Note7-5]		
		-	57	-	mW	[Note7-6]		

[Note7-1] Include Ripple Noise

[Note7-2] Applied overshoot

[Note7-3] Measurement Conditions: Checker pattern (Worst case), PCLK=25MHz

[Note7-4] Measurement Conditions : White pattern, PCLK=25MHz [Note7-5] Measurement Conditions : Black pattern, PCLK=25MHz

[Note7-6] Measurement Conditions: Color ber pattern (following pattern), PCLK=25MHz



**Please refer to specification of "Himax HX8363A" for detail.

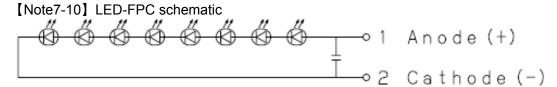
7-2. Back Light Driving Section

Table 5

ble 5						Ta=+25°C, GND=0V
Parameter	Symbol	Min.	Тур.	Max.	Unit	Remarks
LED Voltage	V_{LED}	-	+25.6	-	V	[Note7-8]
LED Current	I _{LED}	-	20	-	mA	
Power Consumption	W _{LED}	-	512	-	mW	[Note7-9]
LED Quantity			8		pcs	
LED Rank		Brightness:W700∼W825			-	NSSW206A
		Chror	naticity:Sbj2	2, Sbk2	-	110077200A

[Note7-8] at I_{LED}=20mA

[Note7-9] $W_{LED}=V_L\times I_L$



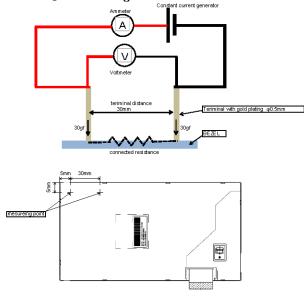
Capacitor: 0.47uF / B / 30V maximum

7-3. Resistance of Rear metal bezel

Initial resistance of Rear metal bezel is 1 Ω or less.

Please refer to Note 7-10 below for measuring method.

[Note7-10] Measuring method



Ammeter: Digital multimeter: Agilent: 34411.A Voltmeter: Digital multimeter: Agilent: 34411.A Constant current generator: Regulated DC Pover Supply KENWOOD PW18-1.3ATS

8. Timing characteristics of input signals

Please refer to specification of "Himax HX8363A" for detail.

8-1.Reset Timing Characteristics

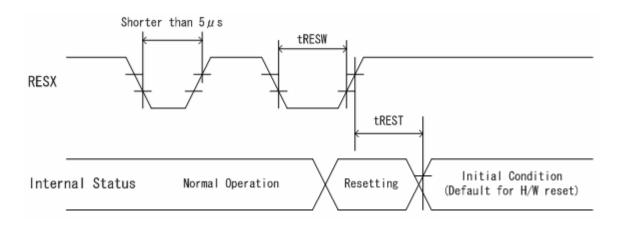
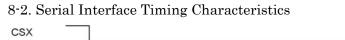


Table 6 Ta=+25°C, GND=0V, VCI=2.75V to 3.3V, VDDIO=1.65V to 3.3V

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
Reset "Low" pulse width	tRESW	10	-	-	μs	
Reset complete time	tREST	-	-	5	ms	【Note8-1】
Reset complete time	u LOT	-	-	120	ms	[Note8-2]

[Note8-1] When reset is applied during sleep in mode

[Note8-2] When reset is applied during sleep out mode



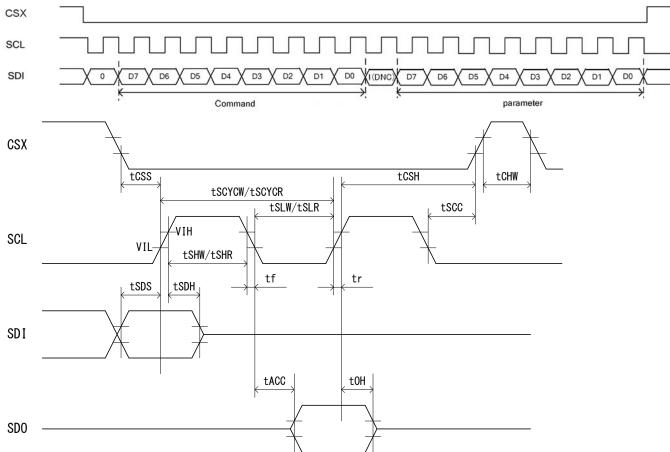


Table 7 Ta=+25°C, GND=0V, VCI=2.75V to 3.3V, VDDIO=1.65V to 3.3V

Table 1 Ta-125 C, GND-0V, VCI-2.75V to 5.5V, VDDIO-1.05V to 5.5V							
Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks	
Serial clock cycle(Write)	tSCYCW	80	-	-	ns		
SCL "H" pulse width(Write)	tSHW	30	-	-	ns		
SCL "L" pulse width(Write)	tSLW	30	-	-	ns		
Data setup time(Write)	tSDS	10	-	-	ns		
Data hold time(Write)	tSDH	10	-	-	ns		
Serial clock cycle(Read)	tSCYCR	150	-	-	ns		
SCL "H" pulse width(Read)	tSHR	60	-	-	ns		
SCL "L" pulse width(Read)	tSLR	60	-	-	ns		
Access time	tACC	10	-	60	ns	[Note8-3]	
Output disable time	tOH	15	-	100	ns	[Note8-3]	
SCL to Chip select	tSCC	30	-	-	ns		
CSX "H" pulse width	tCHW	60	-	-	ns		
CSX-SCL time(Write)	tCSS	30	-	-	ns		
OOX-OOL tillie(vviile)	tCSH	30	-	-	ns		
CSX-SCL time(Read)	tCSS	60	-	-	ns		
COX-SCL time(Read)	tCSH	65	-	-	ns		

[Note8-3] SDO for maximum. CL=30pF. For maximum CL=8pF.

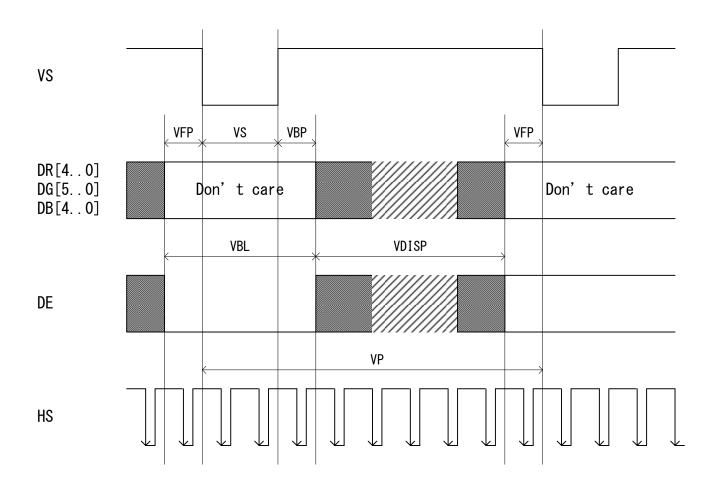


Table 8 Ta=+25°C, GND=0V, VCI=2.75V to 3.3V, VDDIO=1.65V to 3.3V

	14 20 0, 0115 01, 101 21101 to 0.01, 15510 1.001 to 0.01								
Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks			
Vertical cycle	VP	806	809	810	Line				
Vertical low pulse width	VS	2	3	4	Line				
Vertical front porch	VFP	2	3	4	Line				
Vertical back porch	VBP	2	3	4	Line				
Vertical data start point	-	4	6	8	Line	[Note8-4]			
Vertical blanking period	VBL	6	9	10	Line	【Note8-5】			
Vertical active area	-	-	800	-	Line	[Note8-6]			
Vertical refresh rate	VRR	55	60	65	Hz				

[Note8-4] VS+VBP

[Note8-5] VS+VBP+VFP

[Note8-6] VDISP

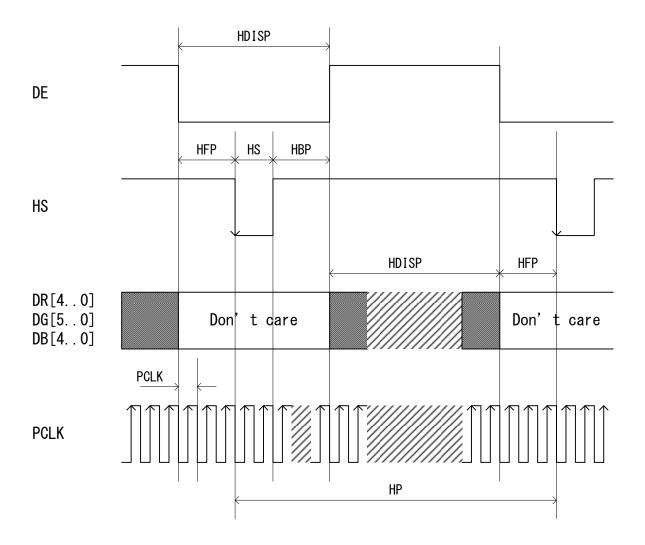


Table 9 Ta=+25°C, GND=0V, VCI=2.75V to 3.3V, VDDIO=1.65V to 3.3V

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
HS cycle	HP	504	507	568	DCK	
HS low pulse width	HS	5	6	256	DCK	
Horizontal back porch	HBP	5	15	256	DCK	
Horizontal front porch	HFP	5	6	256	DCK	
Horizontal data start point	-	19	21	83	DCK	[Note8-7]
Horizontal blanking period	HBLK	24	27	88	DCK	[Note8-8]
Horizontal active area	HDISP	-	480	-	DCK	
Pixel clock frequency	DCK	20.3	24.58	32.2	MHz	[Note8-9]
When RGB I/F is running	DOR	31	40.68	49.2	ns	

[Note8-7] HS+HBP

[Note8-8] HS+HBP+HFP

[Note8-9] VRR=Min.55Hz. – Max.65Hz

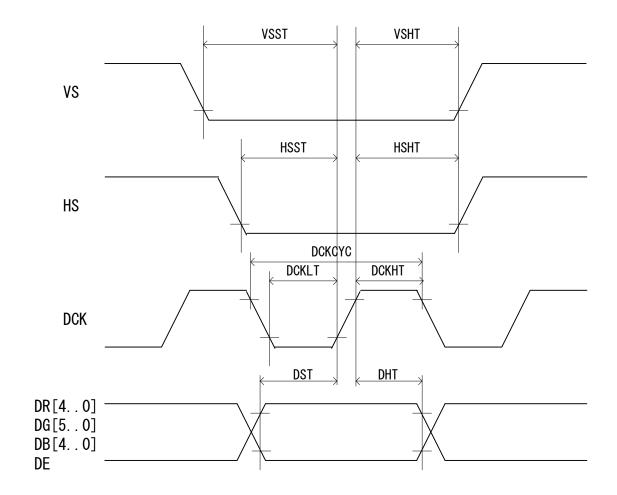


Table 10 Ta=+25°C, GND=0V, VCI=2.75V to 3.3V, VDDIO=1.65V to 3.3V

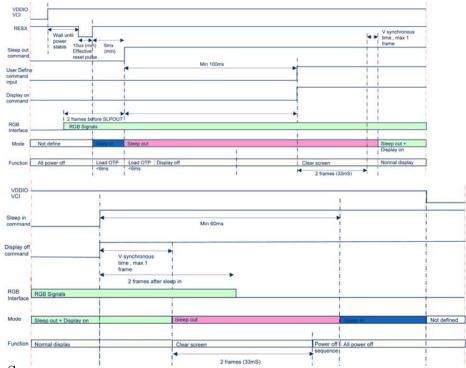
Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remarks
Vertical sync setup time	VSST	5	-	-	ns	
Vertical sync hold time	VSHT	5	-	-	ns	
Horizontal sync setup time	HSST	5	-	-	ns	
Horizontal sync hold time	HSHT	5	-	-	ns	
Pixel clock cycle	DCKCYC	31		49.2	ns	[Note8-12]
When RGB I/F is running	DOROTO	【Note8-10】	-	【Note8-11】		
Pixel clock low time	DCKLT	5	-	-	ns	
Pixel clock high time	DCKHT	5	-	-	ns	
Data setup time	DST	5	-	-	ns	
Data hold time	DHT	5	-	-	ns	

[Note8-10] 32.2MHz

[Note8-11] 20.3MHz

[Note8-12] VRR=Min.55Hz. – Max.65Hz

9. Power Sequence



9-1 Power On Sequence

Table 11

Dogistor										
Register Address	Register Data list	REMARK								
VDDIO(2.6V),VCI(3.0V) ON (anytime VDDIO≦VCI),RESX=H										
WAIT until power stable										
RESX=L										
Wait min.10us(Effective reset pulse)										
RESX=H(Reset release)										
WAIT min. 6ms, RGB signals should be send for 2 frames before SLPOUT command.										
11	**	SLPOUT								
WAIT min. 100ms										
_	FF									
В9	83	User Define Command								
		RGB=888 Setting								
3A	70									
DB	81									
29	**	DISPON								
AIT 2frames(33m	ns) + max1fram	e								
Normal display										
	VCI(3.0V) ON (an WAIT until por RESX ait min.10us(Effer RESX=H(Restals should be sensored WAIT min B9 3A DB 29 AIT 2frames(33m	Address Data list /CI(3.0V) ON (anytime VDDIO≦ WAIT until power stable RESX=L ait min.10us(Effective reset pulse RESX=H(Reset release) als should be send for 2 frames 11 ** WAIT min. 100ms FF 83 63 3A 70 DB 81 29 ** AIT 2frames(33ms) + max1fram								

9-2 Power Off Sequence

Table 12

Table 12									
ITEM	Register Address	Register Data list	REMARK						
Normal display									
Display Off	28	**	DISPOFF						
Sleep In	10	**	SLEEPIN						
WAIT min. 60ms									
(RGB signals should be send for 2 frames after SLPIN command.)									
VDDIO	VDDIO(2.6V).VCI(3.0V) OFF (anytime VDDIO≦VCI)								

10. Input Signals, Basic Display Colors and Gray Scale of Each Color

Table 13

	le 13																									
	Colors &												Data	signa	ls											
	Gray	Gray	R0	R1	R2	R3	R4	R5	R6	R7	G0	G1	G2	G3	G4	G5	G6	G7	B0	B1	B2	ВЗ	B4	B5	В6	В7
	Scale	Scale	LSB							MSB	LSB							MSB	LSB							MSB
	Black	_	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue	_	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
Be	Green	_	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
ısic (Cyan	_	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Basic Color	Red	_	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Magent	_	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	_	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	_	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Black	GS0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
G	仓	GS1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray Scale of Red	Darker	GS2	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Scal	仓	V				1	L							1								`	V			
e of	Û	\downarrow				1	<u>ا</u>							1	_							`	ν <u> </u>			
Red	Brighter	GS253	1	0	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Û	GS254	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	GS255	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Black	GS0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
G.	仓	GS1	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
ay S	Darker	GS2	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0
cale	仓	V				1	L							1								`	V			
of G	Û	V				1	<u>ا</u>							1	/							`	V			
Gray Scale of Green	Brighter	GS253	0	0	0	0	0	0	0	0	1	0	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Û	GS254	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Green	GS255	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Black	GS0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
<u>و</u>	仓	GS1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0
Gray Scale of Blue	Darker	GS2	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0
Scale	仓	V	. ↓					↓							₩											
e of l	Û	V				1	<u>ا</u>							1	/							`	V			
Blue	Brighter	GS253	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	1	1	1	1	1
	Û	GS254	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1
	Blue	GS255	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0 volta	1	1	1	1	1	1	1	1

Low level voltage, 1: High level voltage

Each basic color can be displayed in 256 gray scales from 8 bit data signals. According to the combination of total 24 bit data signals, the 16,777,216-color display can be achieved on the screen.

11. Optical Characteristics

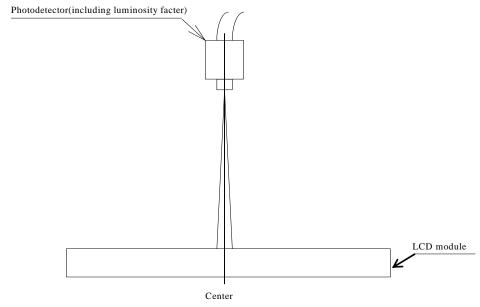
11-1 Driving the Back Light Condition

Table 14 Ta=+25°C

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
Viewing Angle Range	θ21, θ22	OD: 40	70	80	ı	degree	【Note11-1,
	θ11, θ12	CR>10	70	80	-	degree	11-2]
Contrast Ratio	CR	θ=0°	720	870	-	-	(Note11-2)
Response Time	Tr +Td	θ=0°	-	-	35	ms	【Note11-3】
Mulaita Observantiaita	х		0.280	0.310	0.340	-	
White Chromaticity	у		0.290	0.320	0.350	-	
Dad Ohnonatiait.	х		0.616	0.651	0.686	-	
Red Chromaticity	у	0.00	0.310	0.345	0.380	-	
	x	θ=0°	0.227	0.262	0.297	-	
Green Chromaticity	у		0.631	0.666	0.701	-	
Di a Obas sa Cali	х		0.107	0.142	0.177	-	
Blue Chromaticity	у		0.003	0.036	0.071	-	
Brightness	XL1	θ=0°	250	315	-	cd/m²	I _{LED} =20mA
Uniformity	U	θ=0°	75	85	-	%	【Note11-6】
NTSC Ratio	S		80	90	-	%	
Gamma	γ	θ=0°	1.8	2.2	2.6	-	
Flicker	F	θ=0°	-	-	-20	dB	[Note11-7]

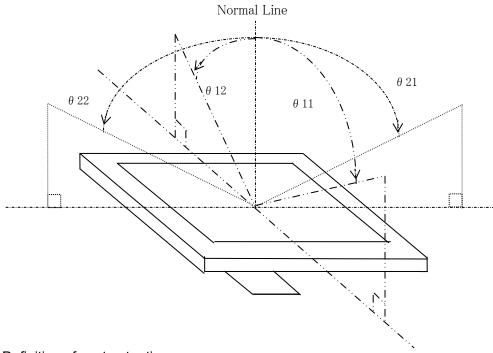
^{*}The measuring method of the optical characteristics is shown by the following figure.

^{*}A measurement device is TOPCON luminance meter SR-3.(Viewing cone1.)



Measuring method for optical characteristics

[Note 11-1] Viewing angle range is defined as follows.



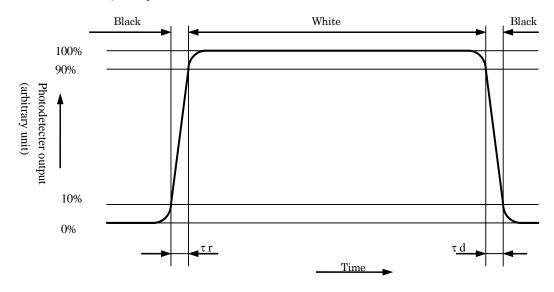
[Note 11-2] Definition of contrast ratio:

The contrast ratio is defined as the follows:

 $Contrast \ ratio \ (CR) = \frac{Luminance (brightness) \ with \ all \ pixels \ white}{Luminance (brightness) \ with \ all \ pixels \ black}$

[Note 11-3] Definition of response time:

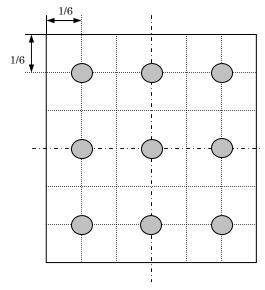
The response time is defined as the following figure and shall be measured by switching the input signal for "black" and "white"



[Note 11-6] Definition of Uniformity.

Uniformity =
$$\frac{\text{Minimum Brightness}}{\text{Maximum Brightness}} \times 100 \, (\%)$$

The brightness should be measured on the 9-points as shown in the following figure.



[Note 11-7] A measurement point is panel center.

Conversion of Flicker ratio : Flicker[dB] = 20log(ACrms/DC)

Frame rate range : 53Hz $\,\sim\,$ 63Hz

12. Reliability Test Items

Table 15

able 1	J	
No.	Test item	Conditions
1	High temperature storage test	Ta = +80°C, 240h
2	Low temperature storage test	Ta = -40°C, 240h
3	High temperature and	Ta = +60°C90%RH, 240h
	high humidity storage test	(No condensation)
4	High temperature operation test	Ta = +60°C, 240h
5	Low temperature operation test	Ta = -20°C, 240h
6	High temperature and high humidity operation test	Ta = +40°C95%RH, 240h (No condensation)
7	Heat shock test	Ta = -40°C(30min) \sim 80°C(30min), 50cycle
_		Black/White block interleave pattern. (Room Temperature, 48 Hours)
8	Image remaining test	Black/White block interleave pattern.
		(40℃, 12 Hours)
9	Shock test	Half Sin, 400 G, 2 ms, 6 faces(±X, ±Y & ±Z), Non-Op
		Sine: 10-500-10Hz, 6 G, 30min (1 cycle: 10~500~10 Hz, 15 min/cycle, 2 cycles), X, Y, Z
10	Vibration test(storage test)	Random: 10-500Hz (6 Grms (0.074 G2/Hz)), 500-2000Hz (-3db/octave), 60min, X, Y, Z
		Sine: 10-500-10Hz, 6 G, 30min (1 cycle: 10~500~10 Hz, 15 min/cycle, 2 cycles), X, Y, Z
11	Vibration test(operation test)	Random: 10-500Hz (6 Grms (0.074 G2/Hz)), 500-2000Hz (-3db/octave), 60min, X, Y, Z
		The box fills with enough talcum powder to cover up UUT and the box only contain 1 unit. Test shall be continued for a period of 1 minute.
12	Anti-Dust test	IEC60529 IP5X Temperature Range:15°C to 35°C Rrelative Humidity:25% TO 75% Air Pressure:86kPa to 106kPa Particle size:50 micrometer Duration time:8 hours
13	FPC Bending Test	Bending 30 times by bending radius R2.0mm and angle=360°(LCD FPC)
14	FPC Insert/Remove test	Insert/Remove LCD FPC for 15 cycles.
15	Low Pressure storage test	40,000 ft, 188 hpa, Room Temperature, 48 Hours.
16	Low Pressure operation test	15,000 ft, 572 hpa, Room Temperature, 48 Hours.
17	LED Life test	Luminance should be larger than half of initial luminance after 5,000 hours operating. (ILED=20 mA, Ta=25°C)
18	Electro static discharge test	±200V, 200pF(0Ω) to Terminals(Contact) (1 time for each terminals) ±8kV, 150pF(330Ω) to Housing bezel(Contact) ±15kV, 150pF(330Ω) to Housing bezel(Air) IEC 61000-4-2

^{*}Ta = Ambient temperature

In the standard condition, there shall be no practical problems that may affect the display function.

^{*}Check items

14. Forwarding form

(a) Piling number of cartons: 8 deep

(b) Package quality in one cartons : 200 pcs

(c) Carton size : 530 mm × 365 mm × 235 mm

(d) Total mass of 1 carton filled with full modules: approximately 8.1kg

Condition for storage

Environment

(1) Temperature : 0~40°C

(2) Humidity: 60%RH or less(at 40°C)

- (3) Atmosphere: Harmful gas, such as acid or alkali which erodes electronic components and/or wires, must not be detected.
- (4) Period : about 3 months
- (5) Opening of the package: In order to prevent the LCD module from breakdown by electrostatic charges, please control the room humidity over 50%RH and open the package taking sufficient countermeasures against electrostatic charges, such as earth, etc.

